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Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf2423-i-sp

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



# 28/40/44-Pin, Enhanced Flash Microcontrollers with 12-Bit A/D and nanoWatt Technology

#### **Power Management Features:**

- · Run: CPU on, Peripherals on
- · Idle: CPU off, Peripherals on
- · Sleep: CPU off, Peripherals off
- Ultra Low 50 nA Input Leakage
- Run mode Currents Down to 11 μA Typical
- Idle mode Currents Down to 2.5 μA Typical
- Sleep mode Current Down to 100 μA Typical
- · Timer1 Oscillator: 900 nA, 32 kHz, 2V
- Watchdog Timer: 1.4 μA, 2V Typical
- Two-Speed Oscillator Start-up

#### Flexible Oscillator Structure:

- · Four Crystal modes, up to 40 MHz
- 4x Phase Lock Loop (PLL) Available for Crystal and Internal Oscillators
- · Two External RC modes, up to 4 MHz
- Two External Clock modes, up to 40 MHz
- · Internal Oscillator Block:
  - Fast wake from Sleep and Idle, 1 μs typical
  - 8 user-selectable frequencies, from 31 kHz to 8 MHz
  - Provides a complete range of clock speeds, from 31 kHz to 32 MHz, when used with PLL
- User-tunable to Compensate for Frequency Drift
- Secondary Oscillator using Timer1 @ 32 kHz
- Fail-Safe Clock Monitor:
  - Allows for safe shutdown if peripheral clock stops

#### Peripheral Highlights:

- 12-Bit, Up to 13-Channel Analog-to-Digital Converter module (A/D):
  - Auto-acquisition capability
  - Conversion available during Sleep mode
- Dual Analog Comparators with Input Multiplexing
- High-Current Sink/Source 25 mA/25 mA
- Three Programmable External Interrupts
- Four Input Change Interrupts
- Up to Two Capture/Compare/PWM (CCP) modules, One with Auto-Shutdown (28-pin devices)
- Enhanced Capture/Compare/PWM (ECCP) module (40/44-pin devices only):
  - One, two or four PWM outputs
  - Selectable polarity
  - Programmable dead time
- Auto-shutdown and auto-restart

#### **Peripheral Highlights (Continued):**

- Master Synchronous Serial Port (MSSP) module Supporting 3-Wire SPI (all four modes) and I<sup>2</sup>C™ Master and Slave modes
- · Enhanced USART module:
  - Support for RS-485, RS-232 and LIN/J2602
  - RS-232 operation using internal oscillator block (no external crystal required)
  - Auto-wake-up on Start bit
  - Auto-Baud Detect (ABD)

#### **Special Microcontroller Features:**

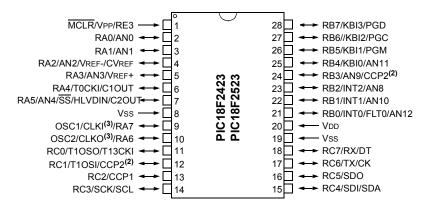
- C Compiler Optimized Architecture: Optional Extended Instruction Set Designed to Optimize Re-Entrant Code
- 100,000 Erase/Write Cycle, Enhanced Flash Program Memory Typical
- 1,000,000 Erase/Write Cycle, Data EEPROM Memory Typical
- Flash/Data EEPROM Retention: 100 Years Typical
- · Self-Programmable under Software Control
- · Priority Levels for Interrupts
- 8 x 8 Single-Cycle Hardware Multiplier
- Extended Watchdog Timer (WDT): Programmable Period, from 4 ms to 131s
- Single-Supply In-Circuit Serial Programming™ (ICSP™) via Two Pins
- · In-Circuit Debug (ICD) via Two Pins
- Operating Voltage Range: 2.0V to 5.5V
- Programmable, 16-Level High/Low-Voltage Detection (HLVD) module: Supports Interrupt on High/Low-Voltage Detection
- Programmable Brown-out Reset (BOR): With Software-Enable Option

Note: This document is supplemented by the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631). See Section 1.0 "Device Overview".

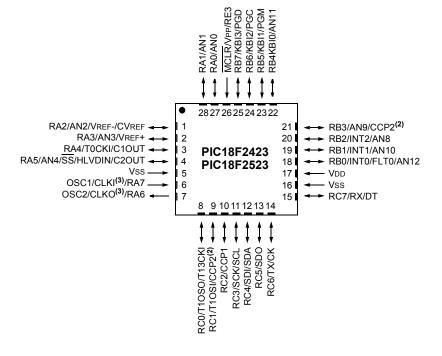
	Progran		gram Memory Data Memory		40 Pit		CCP/	MSSP		RT		<b>T</b>
Device	Flash (bytes)	# Single-Word Instructions	SRAM (bytes)	EEPROM (bytes)	I/O	12-Bit A/D (ch)	ECCP (PWM)	SPI	Master I <sup>2</sup> C™	EUSA	Comp.	Timers 8/16-Bit
PIC18F2423	16K	8192	768	256	25	10	2/0	Υ	Υ	1	2	1/3
PIC18F2523	32K	16384	1536	256	25	10	2/0	Υ	Υ	1	2	1/3
PIC18F4423	16K	8192	768	256	36	13	1/1	Υ	Υ	1	2	1/3
PIC18F4523	32K	16384	1536	256	36	13	1/1	Υ	Υ	1	2	1/3

#### **Pin Diagrams**

#### 28-Pin PDIP, SOIC

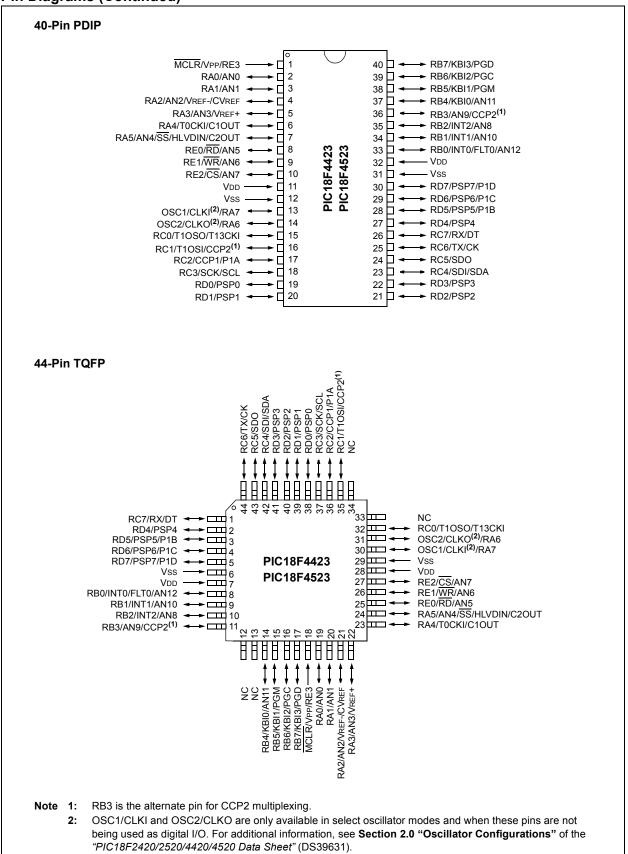


#### 28-Pin QFN<sup>(1)</sup>



- Note 1: It is recommended to connect the bottom pad of QFN package parts to Vss.
  - 2: RB3 is the alternate pin for CCP2 multiplexing.
  - 3: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O. For additional information, see Section 2.0 "Oscillator Configurations" of the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631).

#### Pin Diagrams (Continued)



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An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

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TABLE 1-1: DEVICE FEATURES

Features	PIC18F2423	PIC18F2523	PIC18F4423	PIC18F4523
Operating Frequency	DC – 40 MHz			
Program Memory (Bytes)	16,384	32,768	16,384	32,768
Program Memory (Instructions)	8,192	16,384	8,192	16,384
Data Memory (Bytes)	768	1,536	768	1,536
Data EEPROM Memory (Bytes)	256	256	256	256
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Timers	4	4	4	4
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/Compare/PWM Modules	0	0	1	1
Serial Communications	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART
Parallel Communications (PSP)	No	No	Yes	Yes
12-Bit Analog-to-Digital Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Resets (and Delays)	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT
Programmable High/Low-Voltage Detect	Yes	Yes	Yes	Yes
Programmable Brown-out Reset	Yes	Yes	Yes	Yes
Instruction Set	75 Instructions; 83 with Extended Instruction Set enabled			
Packages	28-Pin PDIP 28-Pin SOIC 28-Pin QFN	28-Pin PDIP 28-Pin SOIC 28-Pin QFN	40-Pin PDIP 44-Pin QFN 44-Pin TQFP	40-Pin PDIP 44-Pin QFN 44-Pin TQFP

TABLE 1-3: PIC18F4423/4523 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Piı	n Numb	er	Pin	Buffer	Description
riii ivailie	PDIP	QFN	TQFP	Type	Type	Description
						PORTC is a bidirectional I/O port.
RC0/T10S0/T13CKI RC0 T10S0 T13CKI	15	34	32	I/O O I	ST — ST	Digital I/O. Timer1 oscillator output. Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2 RC1 T1OSI CCP2 <sup>(2)</sup>	16	35	35	I/O I I/O	ST CMOS ST	Digital I/O. Timer1 oscillator input. Capture 2 input/Compare 2 output/PWM2 output.
RC2/CCP1/P1A RC2 CCP1 P1A	17	36	36	I/O I/O O	ST ST	Digital I/O. Capture 1 input/Compare 1 output/PWM1 output. Enhanced CCP1 output.
RC3/SCK/SCL RC3 SCK	18	37	37	I/O I/O	ST ST	Digital I/O. Synchronous serial clock input/output for SPI mode.
SCL				I/O	I <sup>2</sup> C	Synchronous serial clock input/output for I <sup>2</sup> C™ mode.
RC4/SDI/SDA RC4 SDI SDA	23	42	42	I/O I I/O	ST ST I <sup>2</sup> C	Digital I/O. SPI data in. I <sup>2</sup> C data I/O.
RC5/SDO RC5 SDO	24	43	43	I/O O	ST —	Digital I/O. SPI data out.
RC6/TX/CK RC6 TX CK	25	44	44	I/O O I/O	ST — ST	Digital I/O. EUSART asynchronous transmit. EUSART synchronous clock (see related RX/DT).
RC7/RX/DT RC7 RX DT	26	1	1	I/O I I/O	ST ST ST	Digital I/O. EUSART asynchronous receive. EUSART synchronous data (see related TX/CK).

**Legend:** TTL = TTL compatible input

ST = Schmitt Trigger input with CMOS levels

s I = Input P = Power

CMOS = CMOS compatible input or output

O = Output

 $I^2C = I^2C^{TM}/SMBus$ 

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F4423/4523 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Piı	n Numb	er	Pin	Buffer	Description
Pin Name	PDIP	QFN	TQFP	Туре	Type	Description
						PORTD is a bidirectional I/O port or a Parallel Slave Port (PSP) for interfacing to a microprocessor port. These pins have TTL input buffers when the PSP module is enabled.
RD0/PSP0 RD0 PSP0	19	38	38	I/O I/O	ST TTL	Digital I/O. Parallel Slave Port data.
RD1/PSP1 RD1 PSP1	20	39	39	I/O I/O	ST TTL	Digital I/O. Parallel Slave Port data.
RD2/PSP2 RD2 PSP2	21	40	40	I/O I/O	ST TTL	Digital I/O. Parallel Slave Port data.
RD3/PSP3 RD3 PSP3	22	41	41	I/O I/O	ST TTL	Digital I/O. Parallel Slave Port data.
RD4/PSP4 RD4 PSP4	27	2	2	I/O I/O	ST TTL	Digital I/O. Parallel Slave Port data.
RD5/PSP5/P1B RD5 PSP5 P1B	28	3	3	I/O I/O O	ST TTL	Digital I/O. Parallel Slave Port data. Enhanced CCP1 output.
RD6/PSP6/P1C RD6 PSP6 P1C	29	4	4	I/O I/O O	ST TTL —	Digital I/O. Parallel Slave Port data. Enhanced CCP1 output.
RD7/PSP7/P1D RD7 PSP7 P1D	30	5	5	I/O I/O O	ST TTL —	Digital I/O. Parallel Slave Port data. Enhanced CCP1 output.

**Legend:** TTL = TTL compatible input

ST = Schmitt Trigger input with CMOS levels

O = Output

 $I^2C = I^2C^{TM}/SMBus$ 

CMOS = CMOS compatible input or output

I = Input P = Power

... ------

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

NOTES:

#### REGISTER 2-3: ADCON2: A/D CONTROL REGISTER 2

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	_	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0
bit 7							bit 0

 Legend:
 R = Readable bit
 W = Writable bit
 U = Unimplemented bit, read as '0'

 -n = Value at POR
 '1' = Bit is set
 '0' = Bit is cleared
 x = Bit is unknown

bit 7 **ADFM:** A/D Result Format Select bit

1 = Right justified

0 = Left justified

bit 6 **Unimplemented:** Read as '0'

bit 5-3 ACQT<2:0>: A/D Acquisition Time Select bits

111 = 20 TAD

110 = 16 TAD

101 = 12 TAD 100 = 8 TAD

011 = 6 TAD

010 = 4 TAD

001 **= 2 T**AD

000 = 0 TAD<sup>(1)</sup>

bit 2-0 ADCS<2:0>: A/D Conversion Clock Select bits

111 = FRC (clock derived from A/D RC oscillator)(1)

110 = Fosc/64

101 = Fosc/16

100 = Fosc/4

011 = FRC (clock derived from A/D RC oscillator)(1)

010 = Fosc/32

001 = Fosc/8

000 = Fosc/2

**Note 1:** If the A/D FRC clock source is selected, a delay of one Tcy (instruction cycle) is added before the A/D clock starts. This allows the SLEEP instruction to be executed before starting a conversion.

The analog reference voltage is software selectable to either the device's positive and negative supply voltage (VDD and VSS), or the voltage level on the RA3/AN3/ VREF+ and RA2/AN2/VREF-/CVREF pins.

The A/D Converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

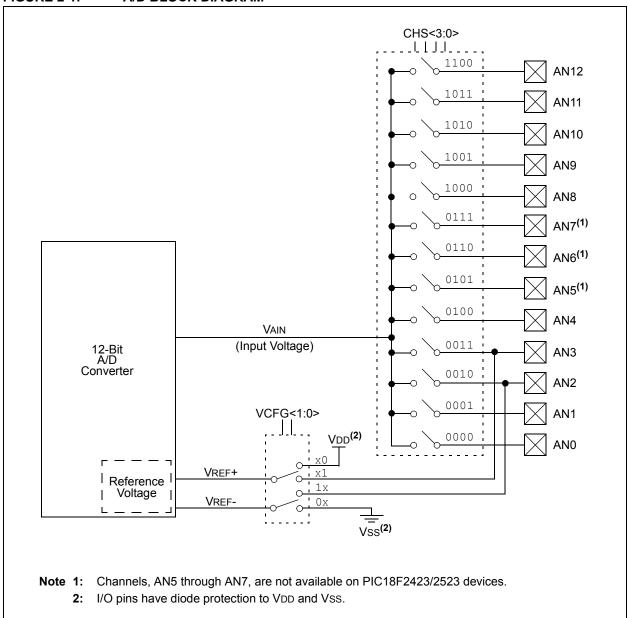
The output of the sample and hold is the input into the converter, which generates the result via successive approximation.

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D Converter can be configured as an analog input or as a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH:ADRESL register pair, the GO/DONE bit (ADCON0<1>) is cleared and A/D Interrupt Flag bit, ADIF, is set.

The block diagram of the A/D module is shown in Figure 2-1.

FIGURE 2-1: A/D BLOCK DIAGRAM



#### 2.2 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set. It also gives users the option of having an automatically determined acquisition time.

Acquisition time may be set with the ACQT<2:0> bits (ADCON2<5:3>), which provide a range of 2 to 20 TAD. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

Manual acquisition time is selected when ACQT<2:0> = 000. When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This option is also the default Reset state of the ACQT<2:0> bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

## 2.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 13 TAD per 12-bit conversion. The source of the A/D conversion clock is software selectable.

There are seven possible options for TAD:

2 Tosc4 Tosc64 Tosc

8 Tosc
 Internal RC Oscillator

16 Tosc

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD. (For more information, see parameter 130 on page 41.)

Table 2-2 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 2-2: TAD vs. DEVICE OPERATING FREQUENCIES

A/D Clock So	A/D Clock Source (TAD)					
Operation	ADCS<2:0>	Maximum Fosc				
2 Tosc	000	2.50 MHz				
4 Tosc	100	5.00 MHz				
8 Tosc	001	10.00 MHz				
16 Tosc	101	20.00 MHz				
32 Tosc	010	40.00 MHz				
64 Tosc	110	40.00 MHz				
RC <sup>(2)</sup>	x11	1.00 MHz <sup>(1)</sup>				

**Note 1:** The RC source has a typical TAD time of 2.5  $\mu$ s.

2: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or a Fosc divider should be used instead; otherwise, the A/D accuracy specification may not be met.

#### 2.8 Use of the CCP2 Trigger

An A/D conversion can be started by the Special Event Trigger of the CCP2 module. This requires that the CCP2M<3:0> bits (CCP2CON<3:0>) be programmed as '1011' and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/DONE bit will be set, starting the A/D acquisition and conversion, and the Timer1 (or Timer3) counter will be reset to zero. Timer1 (or Timer3) is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving ADRESH:ADRESL to the desired location).

The appropriate analog input channel must be selected and the minimum acquisition period is either timed by the user or an appropriate TACQ time is selected before the Special Event Trigger sets the GO/DONE bit (starts a conversion).

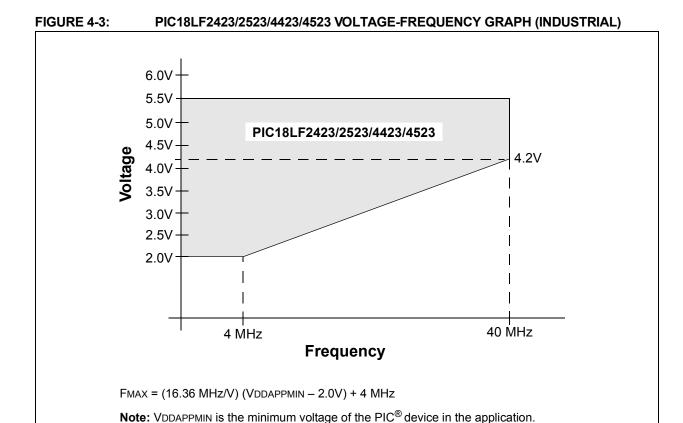
If the A/D module is not enabled (ADON is cleared), the Special Event Trigger will be ignored by the A/D module, but will still reset the Timer1 (or Timer3) counter.

TABLE 2-3: REGISTERS ASSOCIATED WITH A/D OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	(Note 4)
PIR1	PSPIF <sup>(1)</sup>	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	(Note 4)
PIE1	PSPIE <sup>(1)</sup>	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	(Note 4)
IPR1	PSPIP <sup>(1)</sup>	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	(Note 4)
PIR2	OSCFIF	CMIF	_	EEIF	BCLIF	HLVDIF	TMR3IF	CCP2IF	(Note 4)
PIE2	OSCFIE	CMIE	_	EEIE	BCLIE	HLVDIE	TMR3IE	CCP2IE	(Note 4)
IPR2	OSCFIP	CMIP	_	EEIP	BCLIP	HLVDIP	TMR3IP	CCP2IP	(Note 4)
ADRESH	A/D Result Register High Byte								
ADRESL	A/D Result	Register Lo	w Byte						(Note 4)
ADCON0	_	_	CHS3	CHS2	CHS1	CHS0	GO/DONE	ADON	(Note 4)
ADCON1	_	_	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	(Note 4)
ADCON2	ADFM	_	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0	(Note 4)
PORTA	RA7 <sup>(2)</sup>	RA6 <sup>(2)</sup>	RA5	RA4	RA3	RA2	RA1	RA0	(Note 4)
TRISA	TRISA7 <sup>(2)</sup>	TRISA6 <sup>(2)</sup>	PORTA Da	ata Direction	Control Re	gister			(Note 4)
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	(Note 4)
TRISB	PORTB Dat	a Direction (	Control Reg	ister					(Note 4)
LATB	PORTB Dat	a Latch Reg	ister (Read	and Write to	Data Latc	h)			(Note 4)
PORTE <sup>(1)</sup>	_	_	_	_	RE3 <sup>(3)</sup>	RE2	RE1	RE0	(Note 4)
TRISE <sup>(1)</sup>	IBF	OBF	IBOV	PSPMODE	_	TRISE2	TRISE1	TRISE0	(Note 4)
LATE <sup>(1)</sup>	_	_		_	_	PORTE D	ata Latch Re	gister	(Note 4)

**Legend:** — = unimplemented, read as '0'. Shaded cells are not used for A/D conversion.

- Note 1: These registers and/or bits are not implemented on PIC18F2423/2523 devices and are read as '0'.
  - 2: PORTA<7:6> and their direction bits are individually configured as port pins based on various primary oscillator modes. When disabled, these bits read as '0'.
  - 3: RE3 port bit is available only as an input pin when the MCLRE Configuration bit is '0'.
  - **4:** For these Reset values, see **Section 4.0 "Reset"** of the "*PIC18F2420/2520/4420/4520 Data Sheet"* (DS39631).



#### 5.0 PACKAGING INFORMATION

For packaging information, see **Section 28.0 "Packaging Information"** in the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631).

NOTES:

#### **APPENDIX A: REVISION HISTORY**

#### Revision A (June 2006)

Original data sheet for PIC18F2423/2523/4423/4523 devices.

#### **Revision B (January 2007)**

This revision includes updates to the packaging diagrams.

#### Revision C (September 2009)

Electrical specifications updated. Preliminary condition status removed. Converted document to the "mini data sheet" format.

# APPENDIX B: DEVICE DIFFERENCES

The differences between the devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Features	PIC18F2423	PIC18F2523	PIC18F4423	PIC18F4523
Program Memory (Bytes)	16384	32768	16384	32768
Program Memory (Instructions)	8192	16384	8192	16384
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/Compare/PWM Modules	0	0	1	1
Parallel Communications (PSP)	No	No	Yes	Yes
12-Bit Analog-to-Digital Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Packages	28-Pin PDIP 28-Pin SOIC 28-Pin QFN	28-Pin PDIP 28-Pin SOIC 28-Pin QFN	40-Pin PDIP 44-Pin TQFP 44-Pin QFN	40-Pin PDIP 44-Pin TQFP 44-Pin QFN

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#### THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- Product Support Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- General Technical Support Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- Business of Microchip Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

# CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com, click on Customer Change Notification and follow the registration instructions.

#### **CUSTOMER SUPPORT**

Users of Microchip products can receive assistance through several channels:

- · Distributor or Representative
- · Local Sales Office
- Field Application Engineer (FAE)
- · Technical Support
- · Development Systems Information Line

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: http://support.microchip.com

#### PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. Device	X /XX XXX       Temperature Package Pattern Range	Examples:  a) PIC18F4523-I/P 301 = Industrial temp., PDIP package, Extended VDD limits, QTP pattern #301.  b) PIC18F4523-I/PT = Industrial temp., TQFP
Device	PIC18F2423 <sup>(1)</sup> , PIC18F2523 <sup>(1)</sup> , PIC18F4423T <sup>(2)</sup> , PIC18F4523T <sup>(2)</sup> ; VDD range 4.2V to 5.5V PIC18F2423 <sup>(1)</sup> , PIC18F2523 <sup>(1)</sup> , PIC18F4423T <sup>(2)</sup> , PIC18F4523T <sup>(2)</sup> ; VDD range 2.0V to 5.5V	package, Extended VDD limits.  c) PIC18F4523-E/P = Extended temp., PDIP package, normal VDD limits.
Temperature Range	I = $-40$ °C to $+85$ °C (Industrial) E = $-40$ °C to $+125$ °C (Extended)	
Package	PT = TQFP (Thin Quad Flat pack) ML = QFN SO = SOIC SP = Skinny Plastic DIP P = PDIP	Note 1: F = Standard Voltage Range     LF = Wide Voltage Range 2: T = In tape and reel PLCC, and TQFP packages only.
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)	